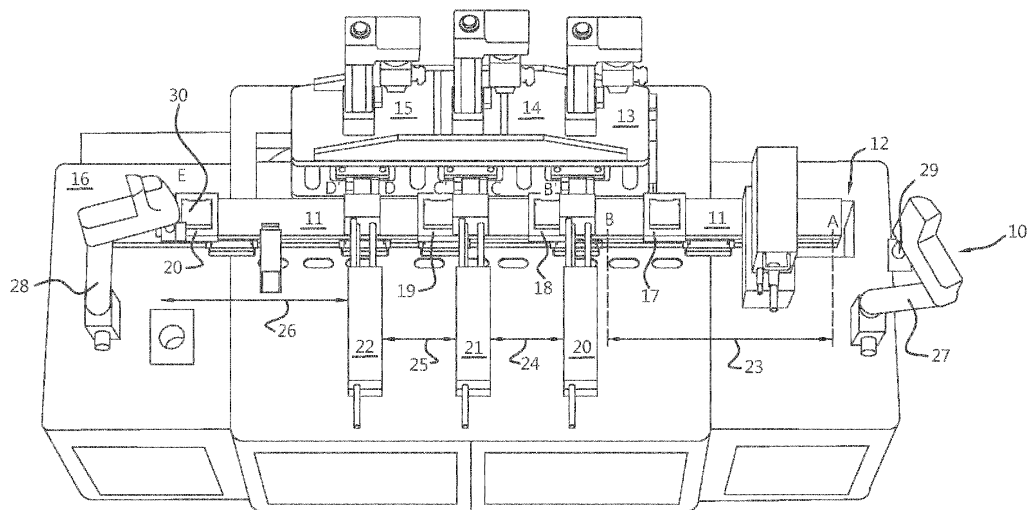




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Fig. 3



(57) Abstract: The present invention relates to a device for post-processing encapsulated integrated circuits, comprising a transit line, extending from an input location along at least one post-processing device for post-processing encapsulated integrated circuits to an output location, at least a first carrier independently movable across the transit line equipped for moving the encapsulated integrated circuits across the transit line between a first receipt location on the transit line and a first release location on the transit line, at least one second carrier independently movable across the transit line, equipped for moving the encapsulated integrated circuits across the transit line between a second receipt location on the transit line and a second release location on the transit line, where the first release location and the second receipt location are at least substantially coincident, at least one finishing device, at the level of the first release location and selected from the group consisting of a punching or trimming device for shortening integrated circuit terminal pins, a

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bending device for bending integrated circuit terminal pins or a punching device for removing an integrated circuit lead frame at least one transfer device, for taking off an encapsulated integrated circuit at the first release location from the first carrier, passing the encapsulated electrical circuit through the first post-processing device and dispensing an encapsulated integrated circuit at the second receipt location to the second carrier.